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218478US-227607-8011-2-PCT

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :  
YASUJI HIRAMATSU ET AL. : ATTN: APPLICATION DIVISION  
SERIAL NO: 10/030,123 :  
FILED: JANUARY 24, 2002 :  
FOR: SEMICONDUCTOR-PRODUCING/  
EXAMINING DEVICE

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

Prior to a first examination on the merits, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend Claims 3 and 4 to read as follows:<sup>1</sup>

3. (Amended) The semiconductor-producing/examining device according to claim 1, wherein  
the connection between said conductor layer and said external terminal, or  
the connection between said another conductor layer and said external terminal  
is performed through a non-oxidizable metal layer.

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<sup>1</sup>A marked-up copy of the amendments is attached hereto.

4. (Amended) The semiconductor-producing/examining device according to claim 1, wherein on a face of said ceramic substrate, which is the face opposite to the face for processing the semiconductor,

the connection between said conductor layer and said external terminal, or

the connection between said another conductor layer and said external terminal is performed.

Please add new Claims 5-8 as follows:

5. (New) The semiconductor-producing/examining device according to claim 2, wherein

the connection between said conductor layer and said external terminal, or

the connection between said another conductor layer and said external terminal is performed through a non-oxidizable metal layer.

6. (New) The semiconductor-producing/examining device according to claim 2, wherein on a face of said ceramic substrate, which is the face opposite to the face for processing the semiconductor,

the connection between said conductor layer and said external terminal, or

the connection between said another conductor layer and said external terminal is performed.

7. (New) The semiconductor-producing/examining device according to claim 3, wherein on a face of said ceramic substrate, which is the face opposite to the face for processing the semiconductor,

the connection between said conductor layer and said external terminal, or

the connection between said another conductor layer and said external terminal

is performed.

8. (New) The semiconductor-producing/examining device according to claim 5, wherein on a face of said ceramic substrate, which is the face opposite to the face for processing the semiconductor,

the connection between said conductor layer and said external terminal, or

the connection between said another conductor layer and said external terminal

is performed.

#### IN THE ABSTRACT

Please amend the Abstract on page 42 to read as follows:

#### ABSTRACT

A semiconductor-producing/examining device that can maintain a preferable connection state for a predetermined period of time and that can easily remove a ceramic substrate from a supporting case. The semiconductor producing/examining device includes a ceramic substrate having a conductor layer formed on the surface thereof or inside thereof and a supporting case. An external terminal is connected to the conductor layer. A connection between the conductor layer and the external terminal is performed such that the external terminal is pressed on the conductor layer or the external terminal is pressed on another conductor layer connected to the conductor layer by using the elastic force and the like of an elastic body.

REMARKS

Favorable consideration of this application, as presently amended, is respectfully requested.

The present Preliminary Amendment is submitted to place the above-identified application in more proper format under United States practice.

By the present Preliminary Amendment Claims 3 and 4 are amended to no longer recite any multiple dependencies. Subject matter of the cancelled multiple dependencies is also now set forth in new dependent Claims 5-8.

The Abstract is also amended to be in more proper format under United States practice.

The present application is believed to be in condition for a full and thorough examination on the merits. An early and favorable consideration of the present application is hereby respectfully requested.

Respectfully submitted,

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<b>Marked-Up Copy</b> Serial No: <u>10/030, 123</u> Amendment Filed on: <u>5-16-2002</u>
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IN THE CLAIMS

Please amend Claims 3 and 4 to read as follows:

--3. (Amended) The semiconductor-producing/examining device according to claim 1 [or 2],

wherein

the connection between said conductor layer and said external terminal, or

the connection between said another conductor layer and said external terminal

is performed through a non-oxidizable metal layer.

4. (Amended) The semiconductor-producing/examining device according to [any of claims 1 to 3] claim 1,

wherein on a face of said ceramic substrate, which is the face opposite to the face for processing the semiconductor,

the connection between said conductor layer and said external terminal, or

the connection between said another conductor layer and said external terminal

is performed.--

Claims 5-8 (New).

IN THE ABSTRACT

Please amend the Abstract on page 42 to read as follows:

--ABSTRACT

[It is an object of the present invention to provide a] A semiconductor-producing/examining device [which] that can maintain a preferable connection state for a predetermined period of time and [which] that can easily remove a ceramic substrate from a supporting case. The [present invention is a] semiconductor producing/examining device [comprising:] includes a ceramic substrate having a conductor layer formed on the surface thereof or inside thereof[;] and a supporting case[; in which an]. An external terminal is connected to the conductor layer[, wherein a]. A connection between the conductor layer and the external terminal is performed such that the external terminal is pressed on the conductor layer or the external terminal is pressed on another conductor layer connected to the conductor layer by using the elastic force and the like of an elastic body.--